## INFORMATION DISCLOSURE CITATION

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Docket Number Opported CO PCI/Physication Sumber ON 2005 FIS920020139US1 Applicant(s)

H. Bernhard Pogge et al.

Filing Date

**Group Art Unit** 

herewith not yet assigned **U.S. PATENT DOCUMENTS** EXAMINER DOCUMENT NUMBER FILING DATE DATE NAME CLASS SUBCLASS INITIAL IF APPROPRIATE /DG/ 4,889,832 12/26/1989 Chatterjee /DG/ 5,268,326 12/7/1993 Lesk et al. /DG/ 6,489,217 12/3/2002 Kalnitsky et al. /DG/ 5,091,331 2/25/1992 Delgado et al. /DG/ 5,627,106 5/6/1997 Hsu /DG/ 6,444,560 9/3/2002 Pogge et al. FOREIGN PATENT DOCUMENTS REF DOCUMENT NUMBER DATE Translation COUNTRY CLASS SUBCLASS NO OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.) J.-Q. Lu et al., "Fabrication of via-chain test structures for 3D IC technology using dielectric glue bonding on 200 mm wafers," Materials Research Society ULSI XVII Conference Proceedings 151 (2002) /DG/ P. Ramm et al., "Interchip via technology by using copper for vertical system integration," Materials Research Society Advanced Metallization Conference 159 (2002) /DG/ EXAMINER DATE CONSIDERED /David E. Graybill/ 08/18/2007 EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and

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*EXAMINER INITIAL	OTHER DOCUMENTS (Including Au		
/DG/	Rahman et al., "Thermal analysis of three of Conference Proceedings 157 (2001)	dimensional integrated circuits," IEEE Intern	ational Interconnect Technology
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